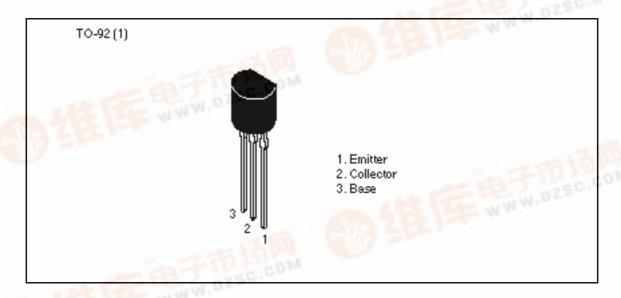
Silicon NPN Epitaxial

# HITACHI

### Application

Low frequency power amplifier, Muting

#### Outline



### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit V	
Collector to base voltage	$V_{CBO}$	30		
Collector to emitter voltage	V <sub>CEO</sub>	15	V	
Emitter to base voltage	V <sub>EBO</sub>	5	V	
Collector current	I <sub>c</sub>	0.7	A	
Collector peak current	i <sub>C(peak)</sub>	1.0	A	
Collector power dissipation	P <sub>c</sub>	500	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	
·				



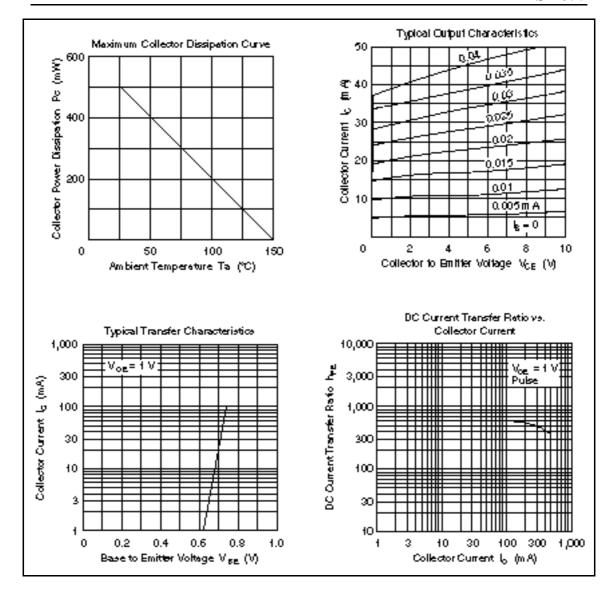
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

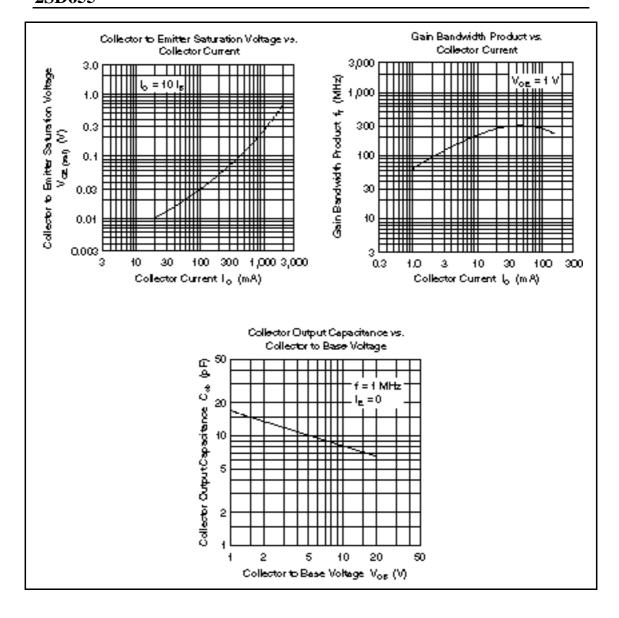
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	15	_	_	V	$I_{\rm C}$ = 1 mA, $R_{\rm BE}$ =
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	1.0	μΑ	$V_{CB} = 20 \text{ V}, I_{E} = 0$
Base to emitter voltage	$V_{BE}$	_	_	1.0	V	$V_{CE} = 1 \text{ V}, I_{C} = 150 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.15	0.5	V	$I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}^{*2}$
DC current transfer ratio	h <sub>FE</sub> *1	250	_	1200		$V_{CE} = 1 \text{ V}, I_{C} = 150 \text{ mA}^{*2}$
Gain bandwidth product	f <sub>T</sub>	_	250	_	MHz	$V_{CE} = 1 \text{ V}, I_{C} = 150 \text{ mA}$

Notes: 1. The 2SD655 is grouped by h<sub>FE</sub> as follows.

2. Pulse test

D	E	F
250 to 500	400 to 800	600 to 1200





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